STL7LN80K5

N-channel 800 V, 0.95 Ω typ., 5 A MDmesh™ K5 Power MOSFET in a PowerFLAT™ 5x6 VHV package

Datasheet - production data

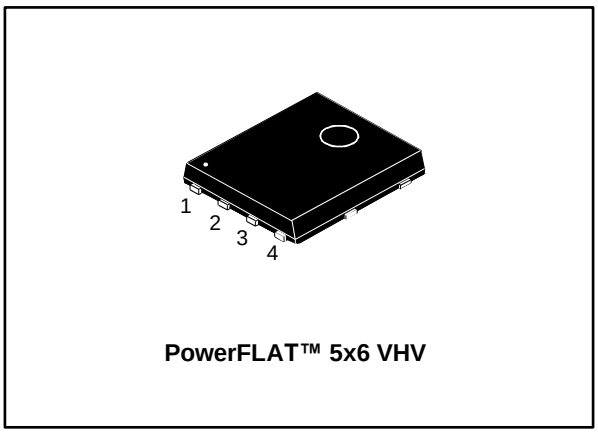
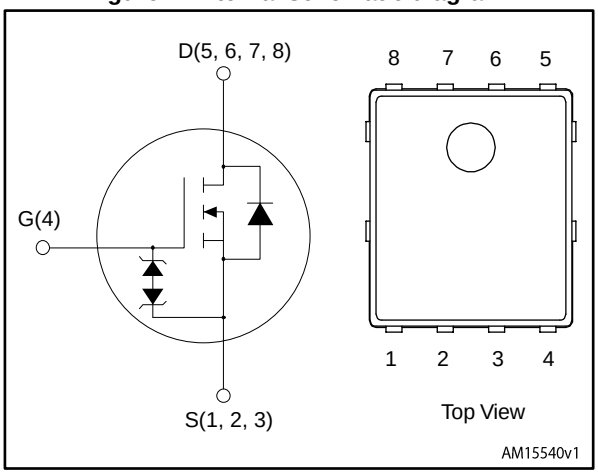


Figure 1: Internal schematic diagram



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STL7LN80K5	800 V	1.15 Ω	5 A

- Industry's lowest $R_{DS(on)}$ x area
- Industry's best figure of merit (FoM)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1: Device summary

Order code	Marking	Package	Packing
STL7LN80K5	7LN80K5	PowerFLAT™ 5x6 VHV	Tape and reel

This is information on a product in full production.

www.st.com

Contents

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	5	A
I_D (1)	Drain current (continuous) at T_C = 100 °C	3.4	A
I_D (2)	Drain current (pulsed)	20	A
P_{TOT}	Total dissipation at T_C = 25 °C	42	W
dv/dt (3)	Peak diode recovery voltage slope	4.5	V/ns
dv/dt (4)	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature range		

Notes:

(1)Limited by maximum junction temperature.

(2)Pulse width limited by safe operating area

(3)$I_{SD} \leq 5$ A, di/dt 100 A/µs; V_{DS} peak < $V_{(BR)DSS}$,V_{DD}= 640 V

(4)$V_{DS} \leq 640$ V

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	3	°C/W
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	59	°C/W

Notes:

(1)When mounted on 1inch² FR-4 board, 2 oz Cu.

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	1.5	A
E_{AS}	Single pulse avalanche energy (starting Tj = 25 °C, $I_D = I_{AR}$, V_{DD} = 50 V)	200	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 5: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	800			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 800 V			1	µA
		V_{GS} = 0 V, V_{DS} = 800 V, T_C = 125 °C			50	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D =100 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 2.5 A		0.95	1.15	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS}= 100 V, f = 1 MHz, V_{GS} = 0 V	-	270	-	pF
C_{oss}	Output capacitance		-	22	-	pF
C_{rss}	Reverse transfer capacitance		-	0.5	-	pF
$C_{o(er)}$ (1)	Equivalent capacitance energy related	V_{DS} = 0 to 640 V, V_{GS} = 0 V	-	17	-	nC
$C_{o(tr)}$ (2)	Equivalent capacitance time related		-	48	-	nC
R_G	Intrinsic gate resistance	f = 1 MHz, I_D=0 A	-	7.5	-	Ω
Q_g	Total gate charge	V_{DD} = 640 V, I_D = 5 A, V_{GS} = 10 V (see *Figure 15: "Test circuit for gate charge behavior"*)	-	12	-	nC
Q_{gs}	Gate-source charge		-	2.6	-	nC
Q_{gd}	Gate-drain charge		-	8.6	-	nC

Notes:

(1)Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

(2)Time related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 400 V, I_D = 2.5 A R_G = 4.7 Ω, V_{GS} = 10 V (see *Figure 14: "Test circuit for resistive load switching times"* and *Figure 19: "Switching time waveform"*)	-	9.3	-	ns
t_r	Rise time		-	6.7	-	ns
$t_{d(off)}$	Turn-off-delay time		-	23.6	-	ns
t_f	Fall time		-	17.4	-	ns

Table 8: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		5	A
I_{SDM} (1)	Source-drain current (pulsed)		-		20	A
V_{SD} (2)	Forward on voltage	I_{SD}= 5 A, V_{GS} = 0 V	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 5 A, di/dt = 100 A/µs, V_{DD} = 60 V (see *Figure 16: "Test circuit for inductive load switching and diode recovery times"*)	-	276		ns
Q_{rr}	Reverse recovery charge		-	2.13		µC
I_{RRM}	Reverse recovery current		-	15.4		A
t_{rr}	Reverse recovery time	I_{SD} = 5 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_j = 150 °C (see *Figure 16: "Test circuit for inductive load switching and diode recovery times"*)	-	402		ns
Q_{rr}	Reverse recovery charge		-	2.79		µC
I_{RRM}	Reverse recovery current		-	13.9		A

Notes:

(1)Pulse width is limited by safe operating area

(2)Pulsed: pulse duration = 300 µs, duty cycle 1.5%

Table 9: Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	I_{GS} = ±1 mA, I_D = 0 A	30	-		V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection,thus eliminating the need for additional external componentry.

2.2 Electrical characteristics (curves)

Figure 2: Safe operating area

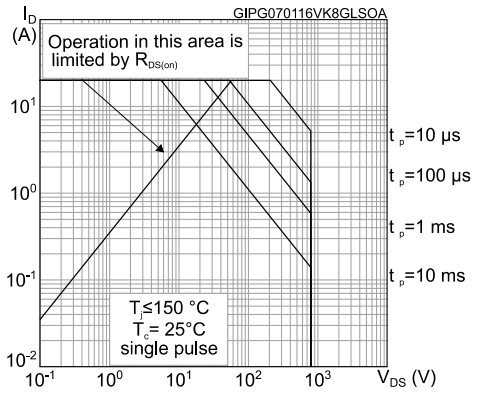


Figure 3: Thermal impedance

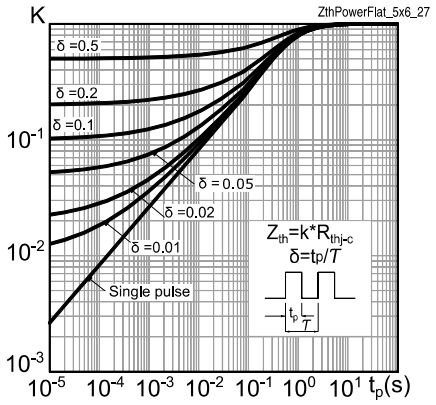


Figure 4: Output characteristics

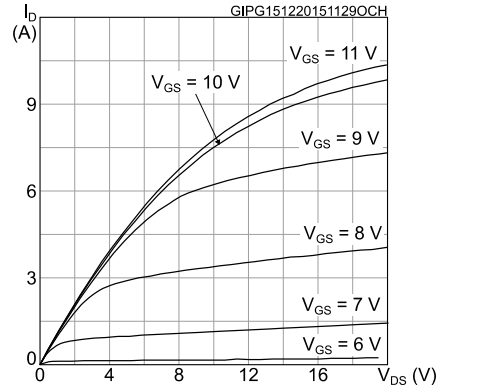


Figure 5: Transfer characteristics

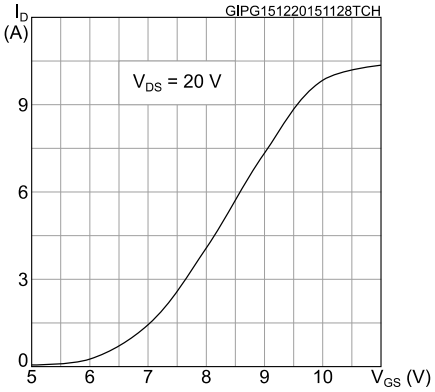


Figure 6: Gate charge vs gate-source voltage

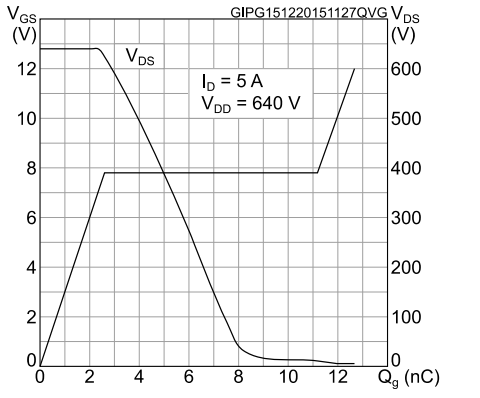


Figure 7: Static drain-source on-resistance

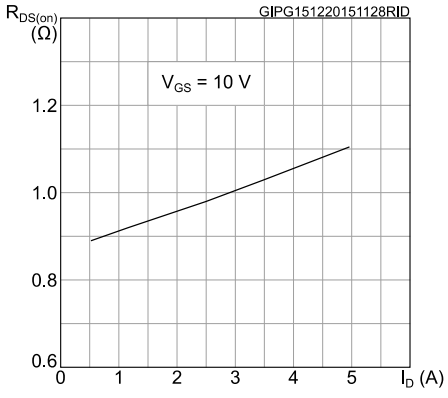


Figure 8: Capacitance variations

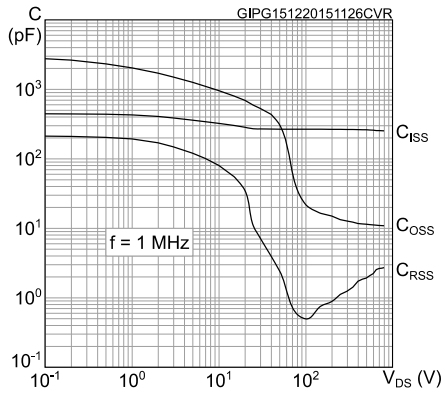


Figure 9: Normalized gate threshold voltage vs temperature

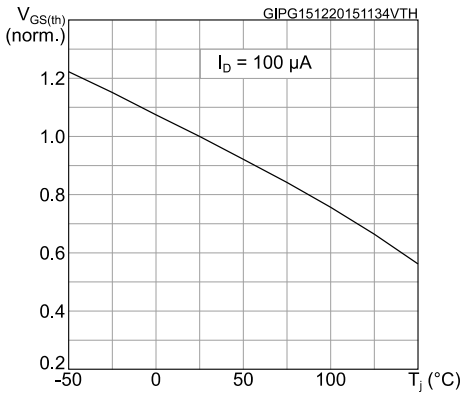


Figure 10: Normalized $V_{(BR)DSS}$ vs temperature

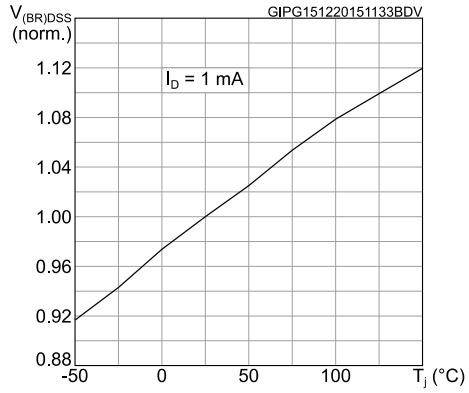


Figure 11: Normalized on-resistance vs temperature

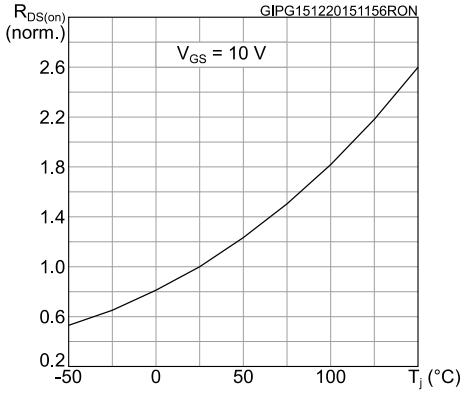


Figure 12: Source-drain diode forward characteristics

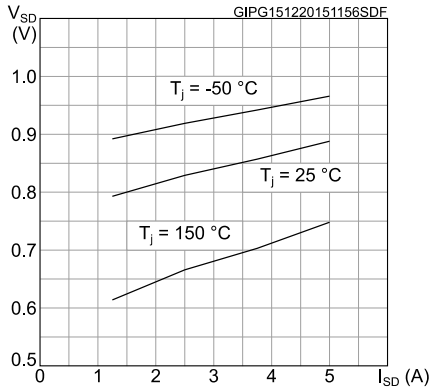
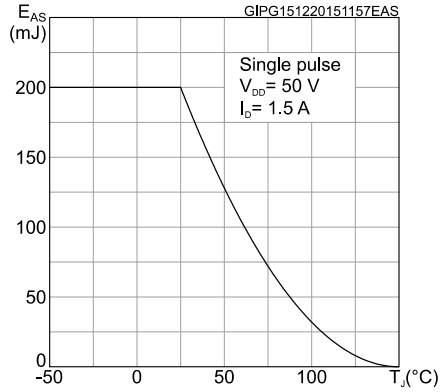


Figure 13: Maximum avalanche energy vs starting T_J



3 Test circuits

Figure 14: Test circuit for resistive load switching times

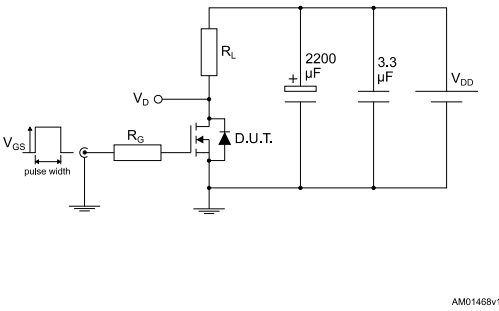


Figure 15: Test circuit for gate charge behavior

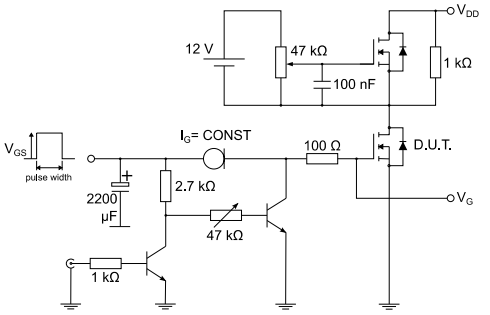


Figure 16: Test circuit for inductive load switching and diode recovery times

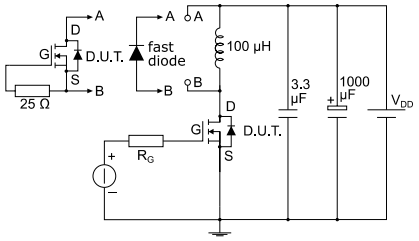


Figure 17: Unclamped inductive load test circuit

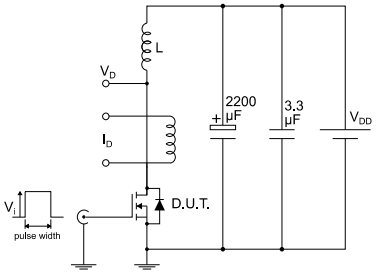


Figure 18: Unclamped inductive waveform

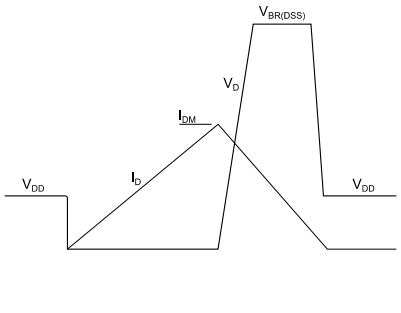
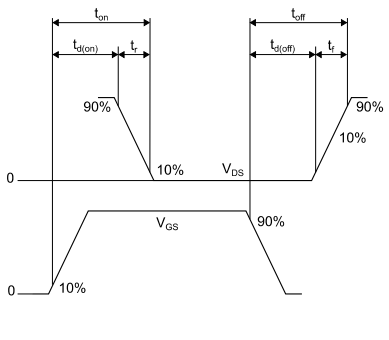


Figure 19: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 VHV package information

Figure 20: PowerFLAT™ 5x6 VHV Package outline

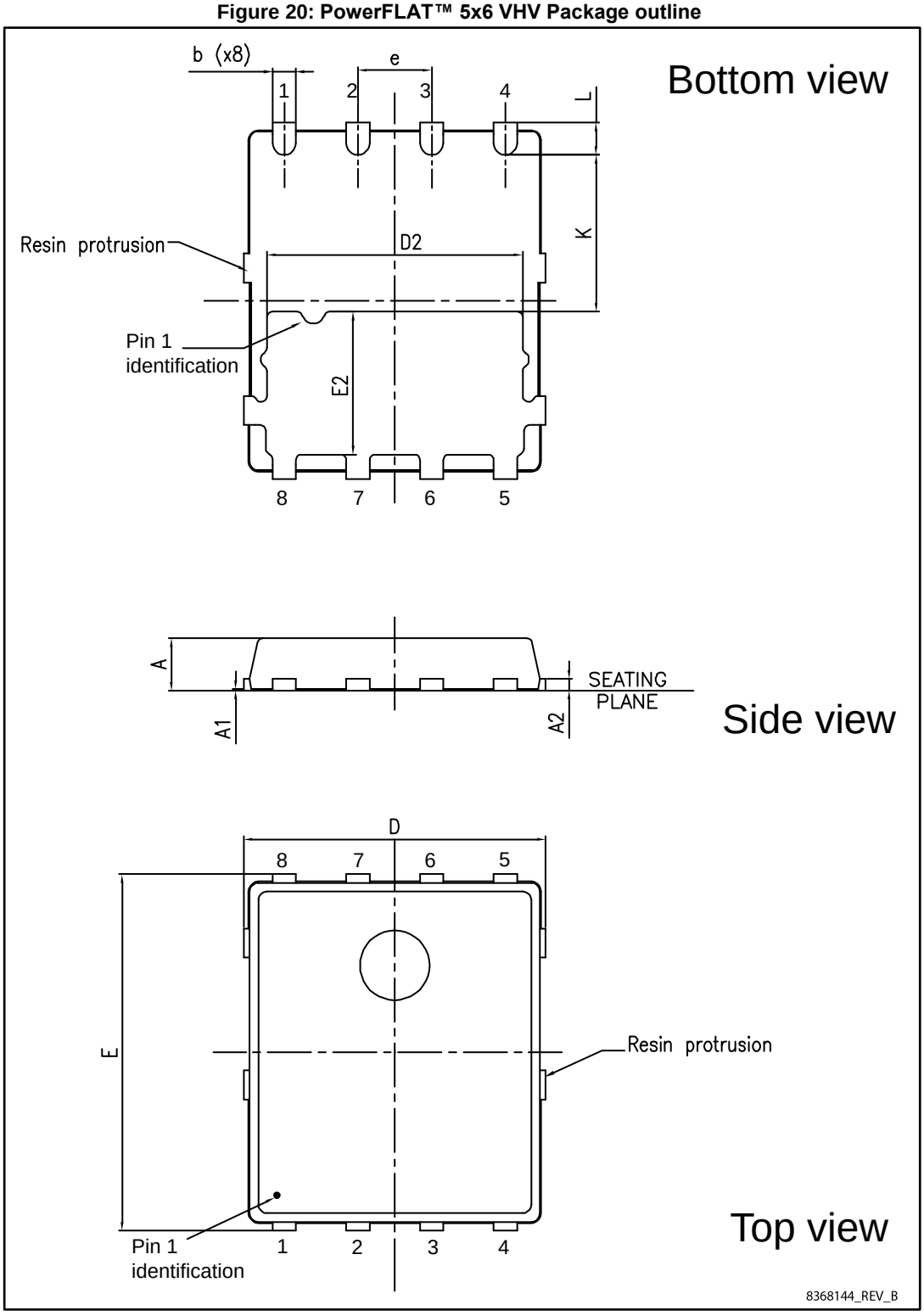
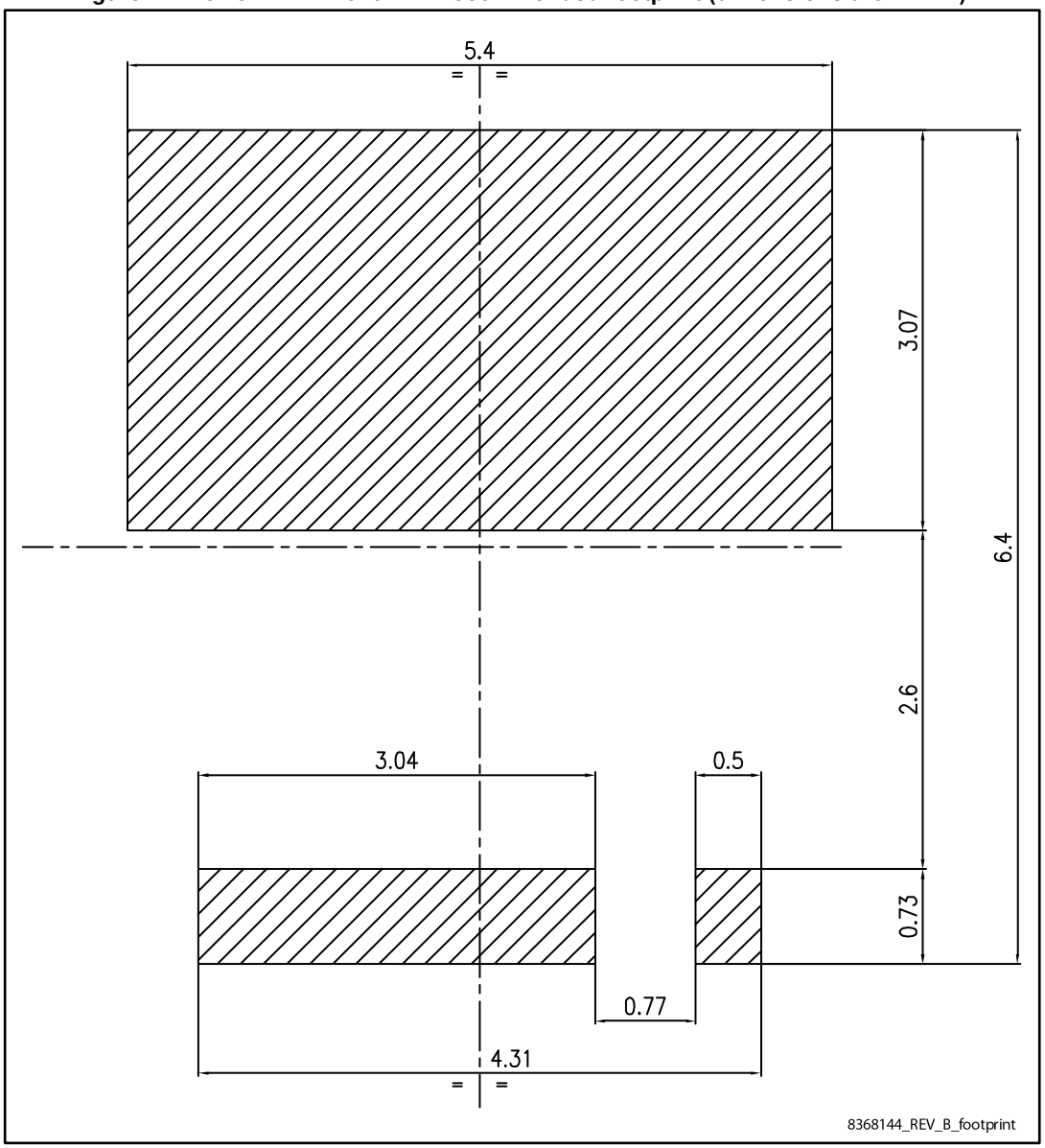


Table 10: PowerFLAT™ 5x6 VHV package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D	5.00	5.20	5.40
E	5.95	6.15	6.35
D2	4.30	4.40	4.50
E2	2.40	2.50	2.60
e		1.27	
L	0.50	0.55	0.60
K	2.60	2.70	2.80

Figure 21: PowerFLAT™ 5x6 VHV recommended footprint (dimensions are in mm)



4.2 PowerFLAT™ 5x6 packing information

Figure 22: PowerFLAT™ 5x6 tape (dimensions are in mm)

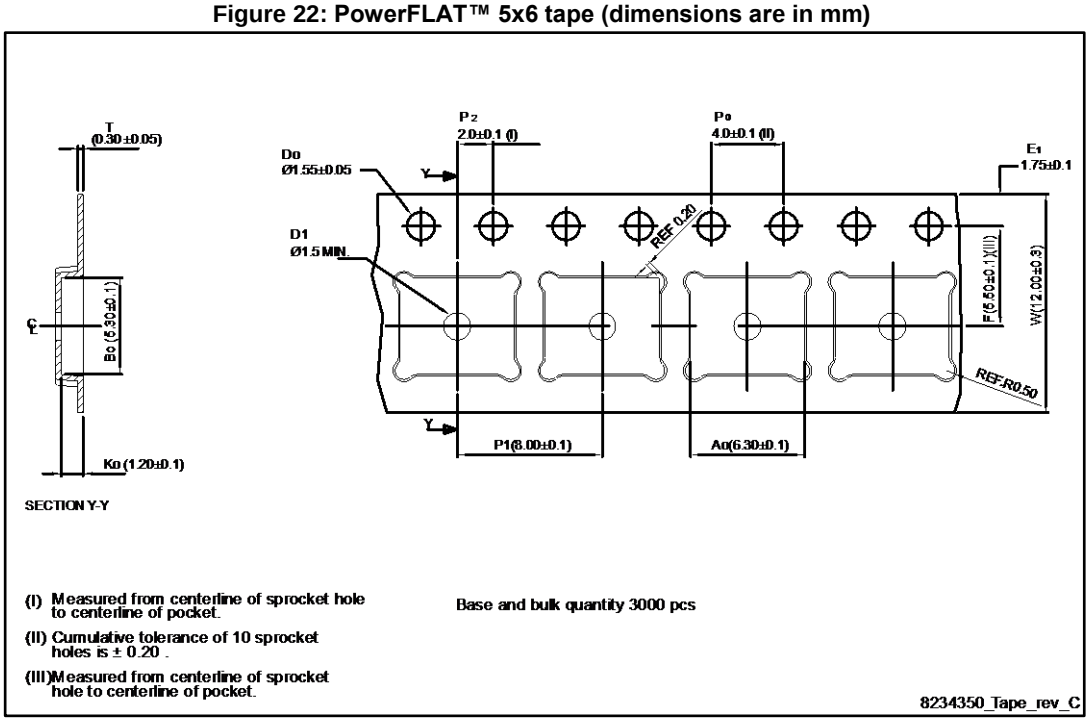


Figure 23: PowerFLAT™ 5x6 package orientation in carrier tape

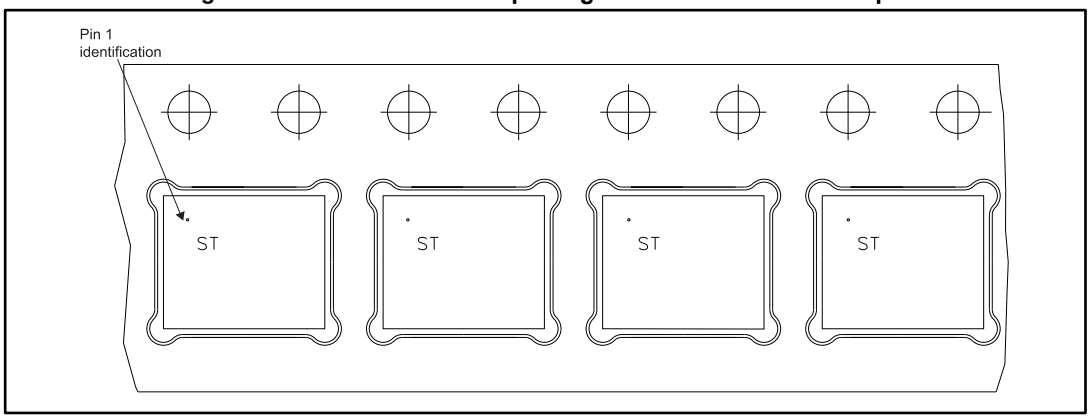
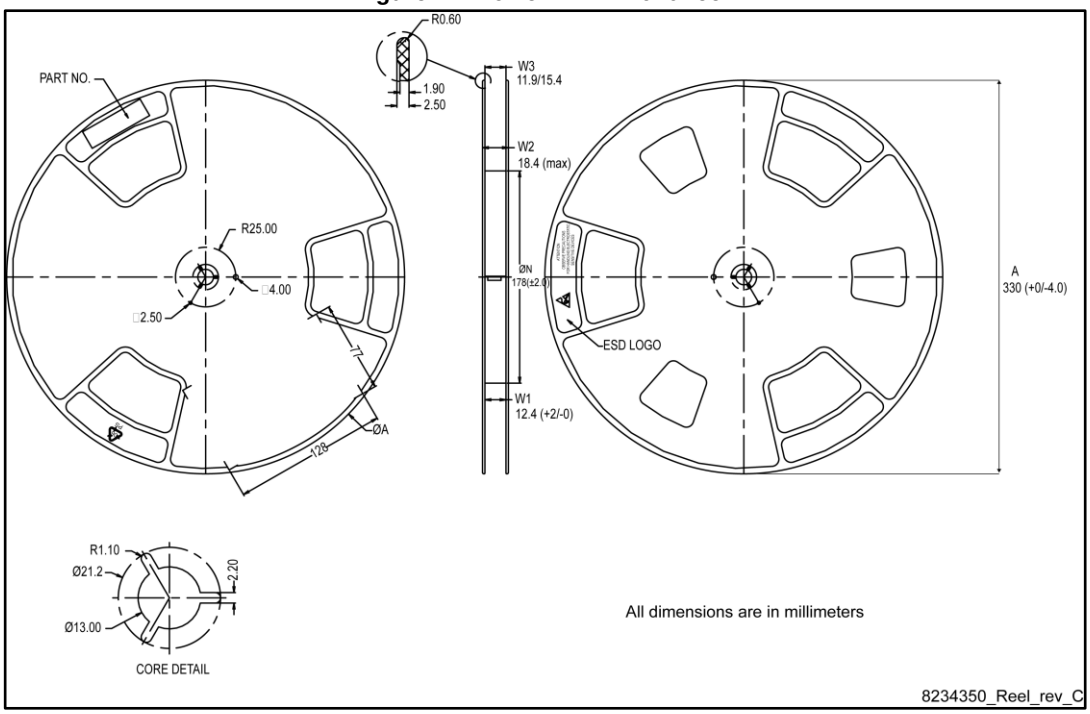


Figure 24: PowerFLAT™ 5x6 reel



5 Revision history

Table 11: Document revision history

Date	Revision	Changes
07-Jan-2016	1	First release.
26-Jan-2016	2	Modified: *Table 2: "Absolute maximum ratings"* Minor text changes

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved